Product Specification

Product:	**Dielectric Paste**
Part Number:	**07HTGT90**

Application Scope :

This paste is suitable for use as an interlayer dielectric paste in multilayer wiring of thick-film circuits and for via filling and insulation.

Usage Conditions :

Substrate	Thick film circuit, alumina ceramic, zirconia ceramic
Usage Method	Printing, 200-250 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted according to actual conditions).
Firing Condition	The sintering temperature is 900~1050°C (recommended value) and the sintering time is 10 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤8μm	FOG test
2	Viscosity	180~380Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R), 10 rpm, 25±1°C
3	Appearance	Achromatic colour, Transparent	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1）

Characteristics		Standard	Test Method And Conditions
4	Appearance	Compact and dense	Visual
5	Capacitance of unit	≤3.0PF/mm^2	KT2618 type
6	Wastage of insulation	＜1%	KT2618 type
7	Insulation Resistance	＞10^{9}Ω（500VDC, 25°C）	RCJ-3 type
8	Breakdown Voltage	＞2000VAC, 25°C	CS2673A type
9	Dielectric Constant(ε)	9～15	Calculation

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.